

C1812C123M2TACTU

Aliases (C1812C123M2TAC7800) SMD Comm X8G HT150C, Ceramic, 0.012 uF, 20%, 200 VDC, X8G, SMD, MLCC, High Temperature, Ultra-Stable, 1812, 2.3 mm



General Information	
Series	SMD Comm X8G HT150C
Style	SMD Chip
Description	SMD, MLCC, High Temperature, Ultra-Stable
Features	High Temperature, Ultra-Stable
RoHS	Yes
Termination	Tin
Marking	No
AEC-Q200	No
Typical Component Weight	67 mg
Shelf Life	78 Weeks
MSL	1

Dimensions	
Chip Size	1812
L	4.5mm +/-0.3mm
W	3.2mm +/-0.3mm
Т	1mm +/-0.10mm
S	2.3mm MIN
В	0.6mm +/-0.35mm

1000

Packaging Quantity

W	3.2mm +/-0.3mm	Tolerance
Т	1mm +/-0.10mm	Voltage DC
S	2.3mm MIN	Dielectric Withstand
В	0.6mm +/-0.35mm	Temperature Range
		Temp. Coefficient
Packaging Specifications		Capacitance Chang
Packaging	T&R, 180mm, Plastic Tape	Reference to +25°C

Specifications	
Capacitance	0.012 uF
Measurement Condition	1 kHz 1.0Vrms
Tolerance	20%
Voltage DC	200 VDC
Dielectric Withstanding Voltage	500 VDC
Temperature Range	-55/+150°C
Temp. Coefficient	X8G
Capacitance Change with Reference to +25°C and 0 VDC Applied (TCC)	30 ppm/C, 1kHz 1.0Vrms
Dissipation Factor	0.1% 1 kHz 1.0Vrms
Aging Rate	0% Loss/Decade Hour: Referee Time is 1000 Hours
Insulation Resistance	83.3333 GOhms

Statements of suitability for certain applications are based on our knowledge of typical operating conditions for such applications, but are not intended to constitut	te - and
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